

Design Considerations of UFS & e.MMC Controllers Compliance & Compatibility

Yuping Chung

Arasan Chip systems, Inc.
San Jose, CA



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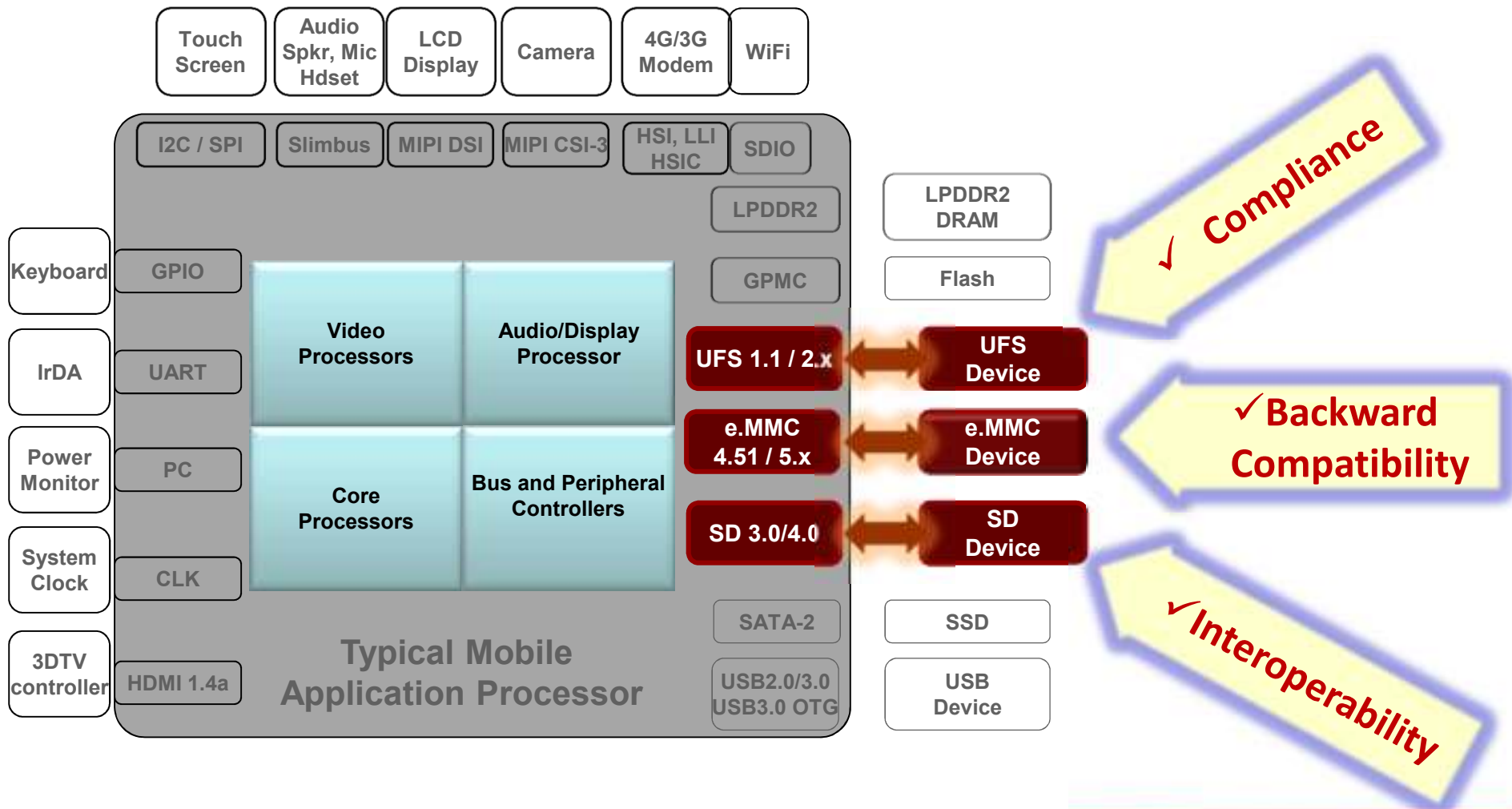
JEDEC

Global Standards for the Microelectronics Industry

Agenda

- Mobile Storage in SoC
- Challenges to Mobile Storage Controller Designs
- Enabling Mobile Storage Design Ecosystem
- Summary

Multiple Mobile Storage Interfaces in Application Processor

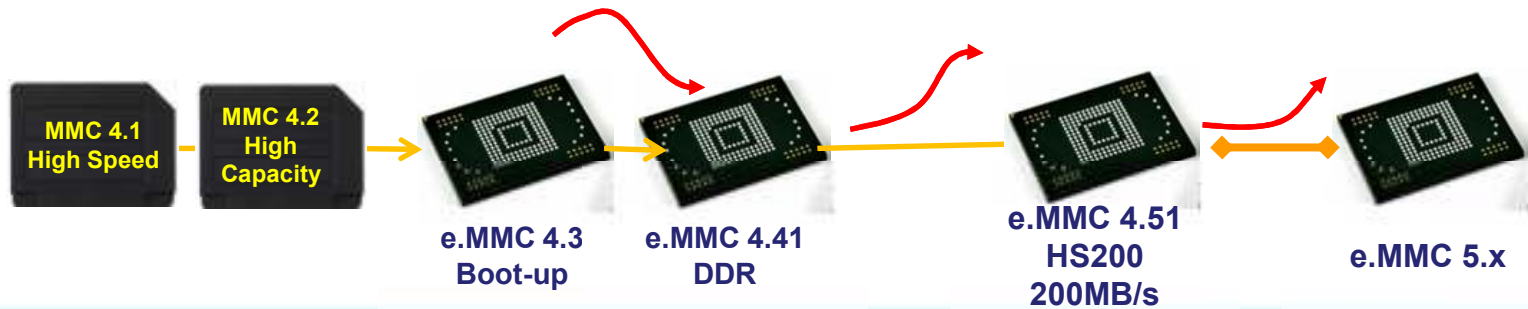


Mobile Storage Evolution Faster Than Ever

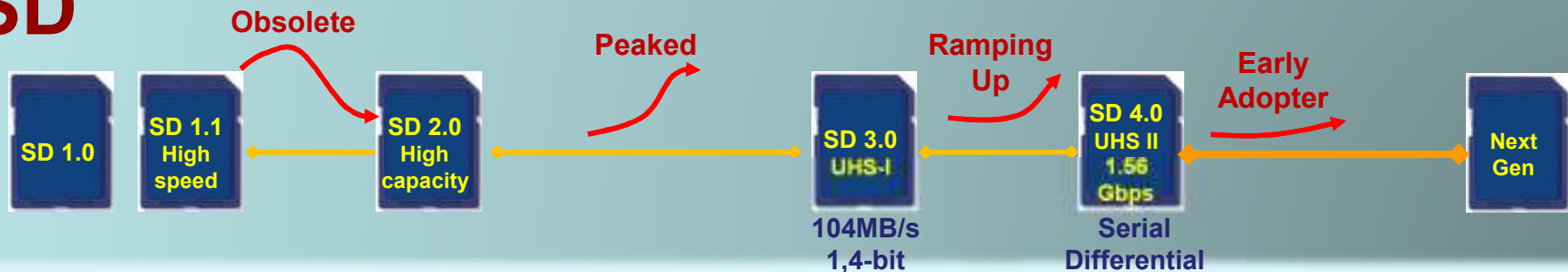
UFS



e.MMC



SD



2003

2006

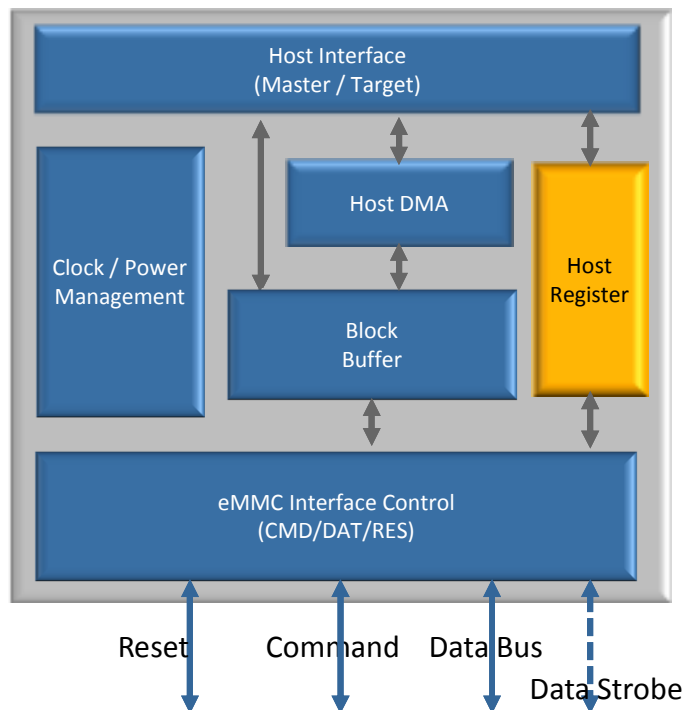
2009

2011

2012

2013

Challenges of Backward Compatibility e.MMC



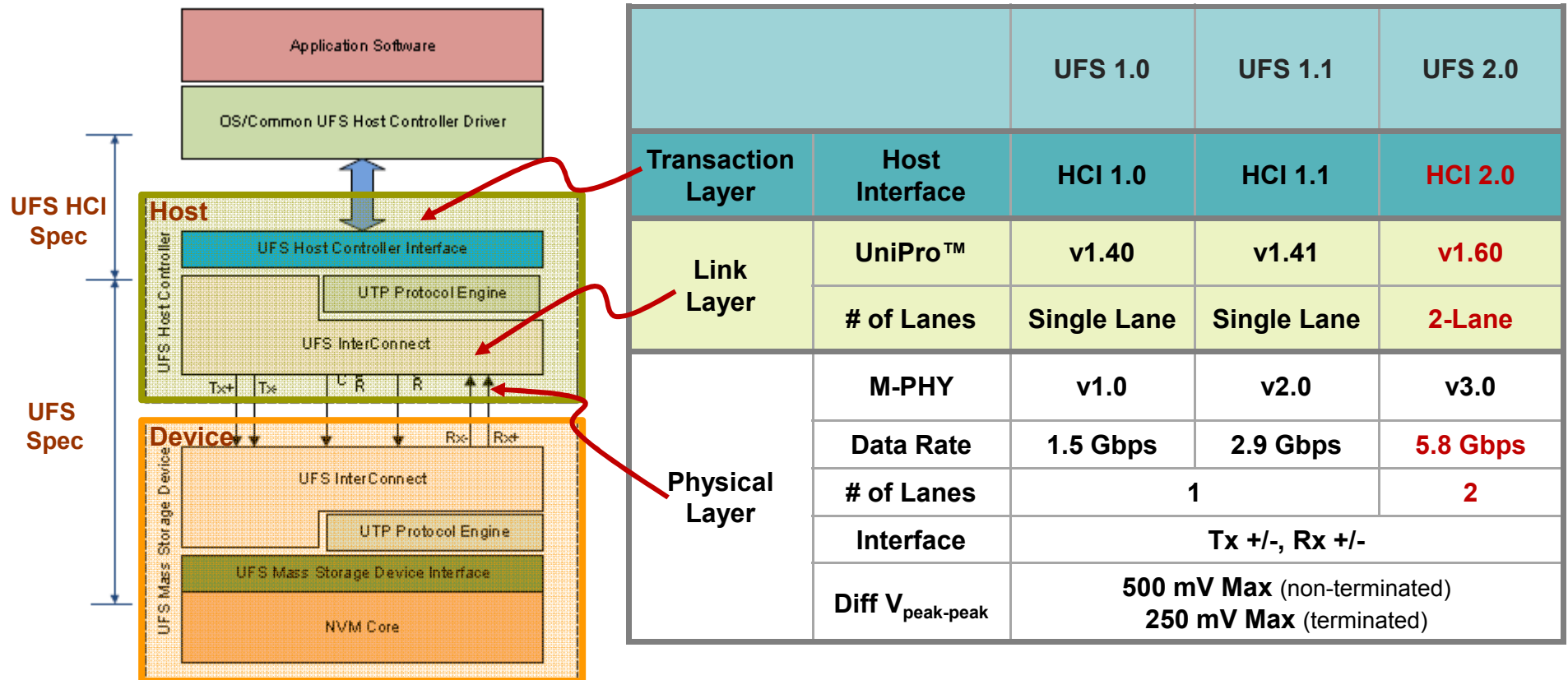
	e.MMC 4.41	e.MMC 4.51	e.MMC5.0
Max Throughput	High Speed 832 Mbps	HS200 1.6 Gbps	HS400 3.2 Gbps
Data Lines	4 or 8-bit		8-bit
Signal Count	10 Pins		11 Pins (Data Strobe)
IO Voltages	1.2 V / 1.8 V 3 V		1.2 V / 1.8 V
Interface	DDR-52	SDR-200	DDR-200
Data Strobe	No		Yes
Tuning (Read)	No	Yes	
Clock (MHz)	0 – 52 MHz	0 – 200 MHz	

e.MMC Compliance

- e.MMC Device spec published by JEDEC
- Compliance can be done through 3rd party Compliance Testers
 - No formal compliance guidelines

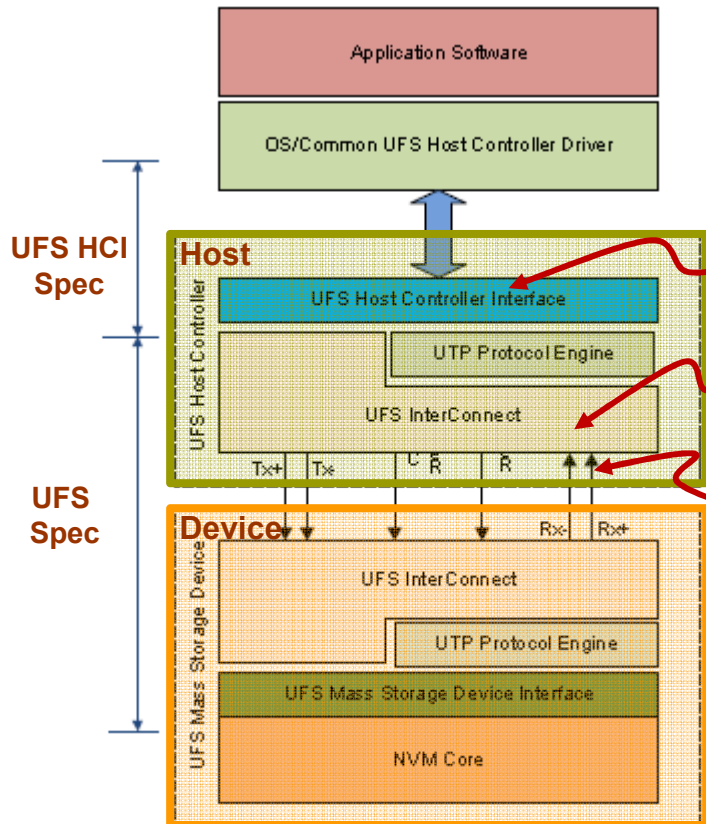
Challenges of Backward Compatibility

UFS



Source: JEDEC

UFS 1.1 Compliance



Source: JEDEC

	Protocol	Rev.	Test Spec	Certification
Transaction Layer	UFS	1.1	UFS Test Spec v1.0	UFSA
Link Layer	UniPro	1.41	UniPro CTS_v1.0_r01	MIPI / UNH-OL
PHY Layer	M-PHY	2.0	M-PHY CTS_v0.99	

Design Challenges

Can I have all these validated before starting my SoC design?

2. Backward Compatibility

e.MMC 4.3 → 4.4 → 4.5 → 4.51 → 5.x

UFS 1.0 → 1.1 → 2.x

UniPro 1.40 → 1.41 → 1.6x

M-PHY 1.0 → 2.0 → 3.x

SD 2.0 → 3.0 → 4.0 → 4.x

UHS-II → UHS-?

3. Inter-Operability

Smart Phones
Tablets
Set top box
Phablet

Data/File Transfer

Read/Write Commands

Link Initialization

UFS Device 1
UFS Device 2
e.MMC Device 1
e.MMC Device 2

JEDEC

e.MMC

UFS

Physical Layer

mipi

UFSA

Link Layer

UniPro™

M-PHY™

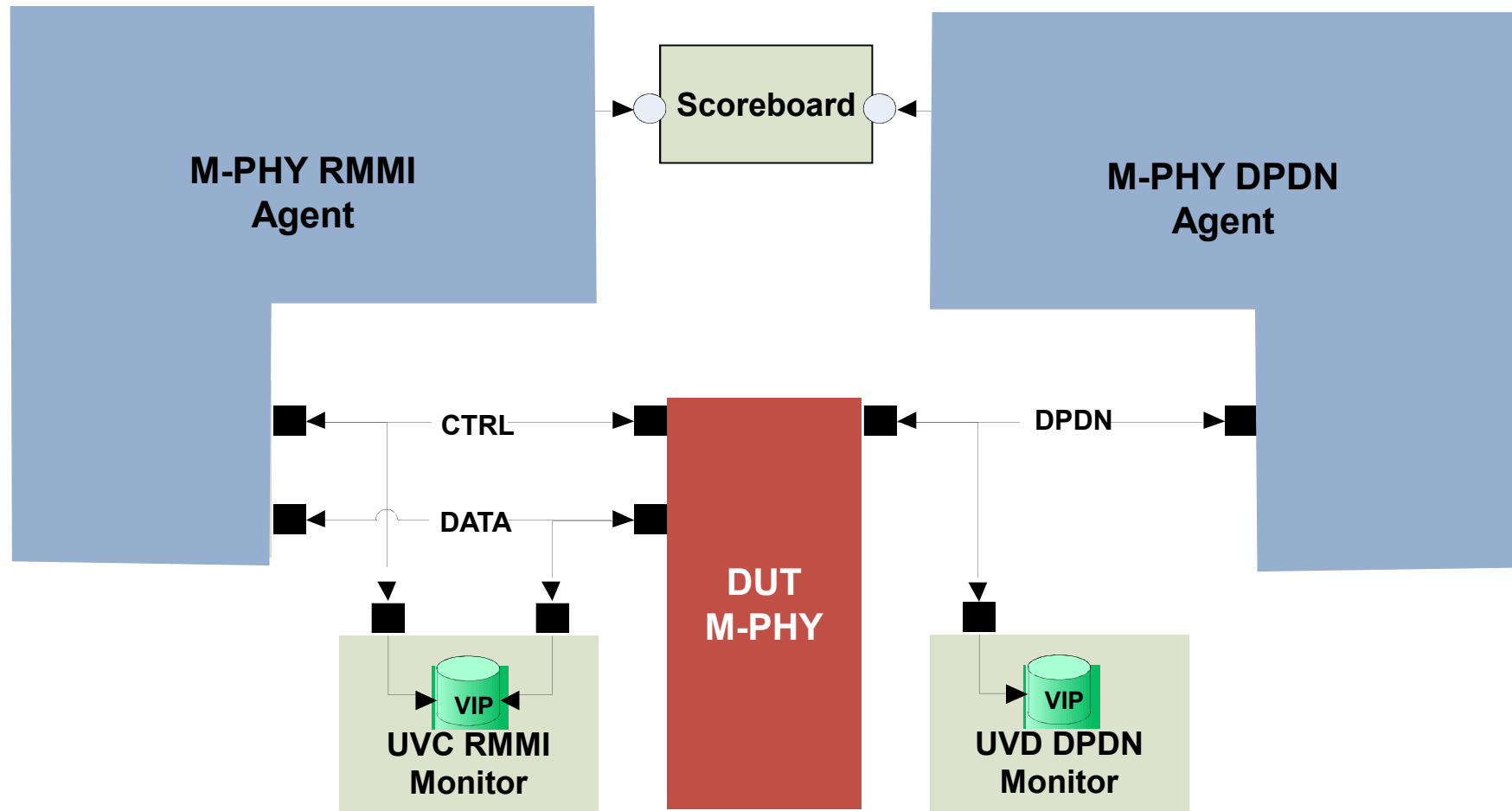
SDA

Application Layer

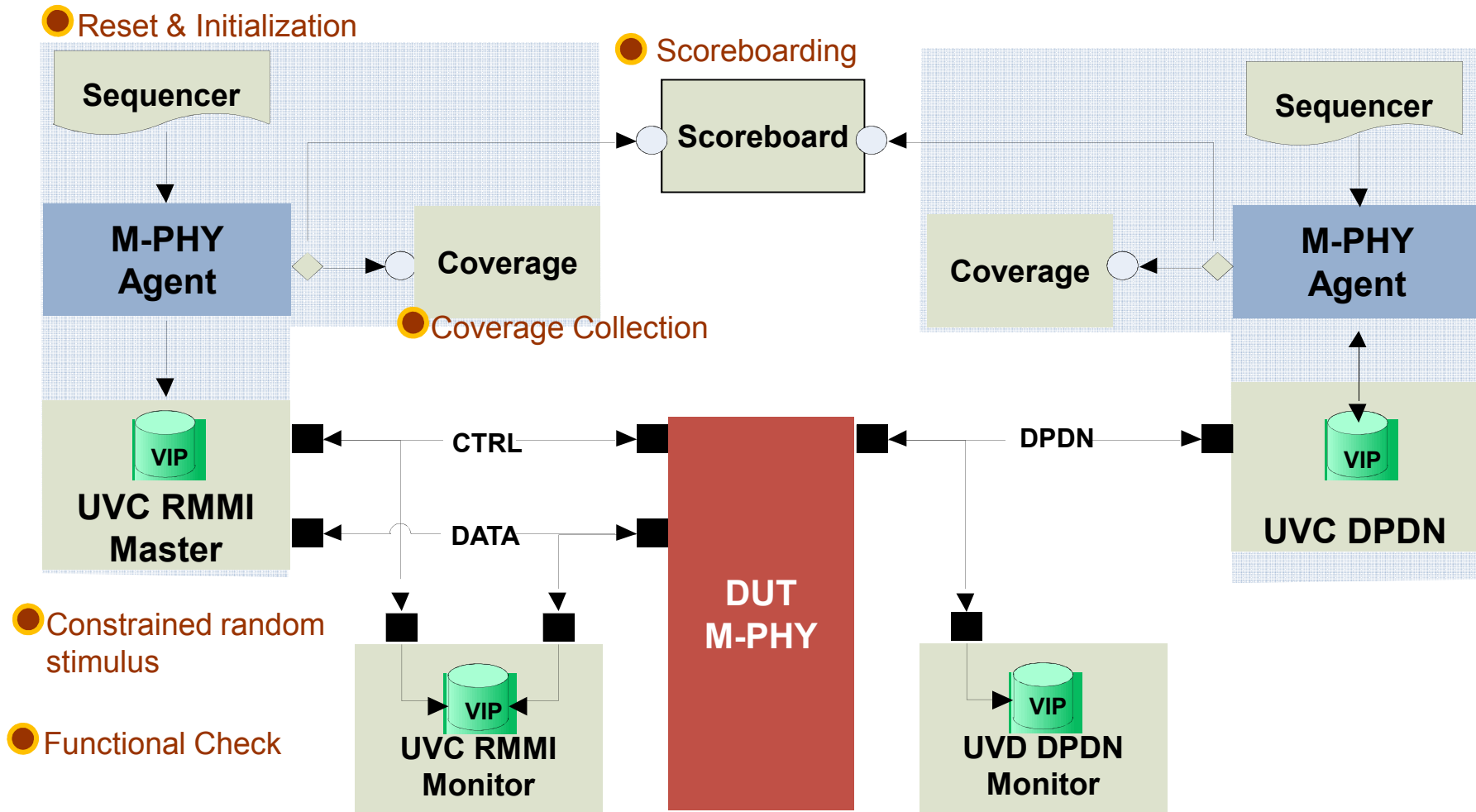
SD SDIO

1. Compliance to Industry Standard(s)

M-PHY Verification Before Silicon

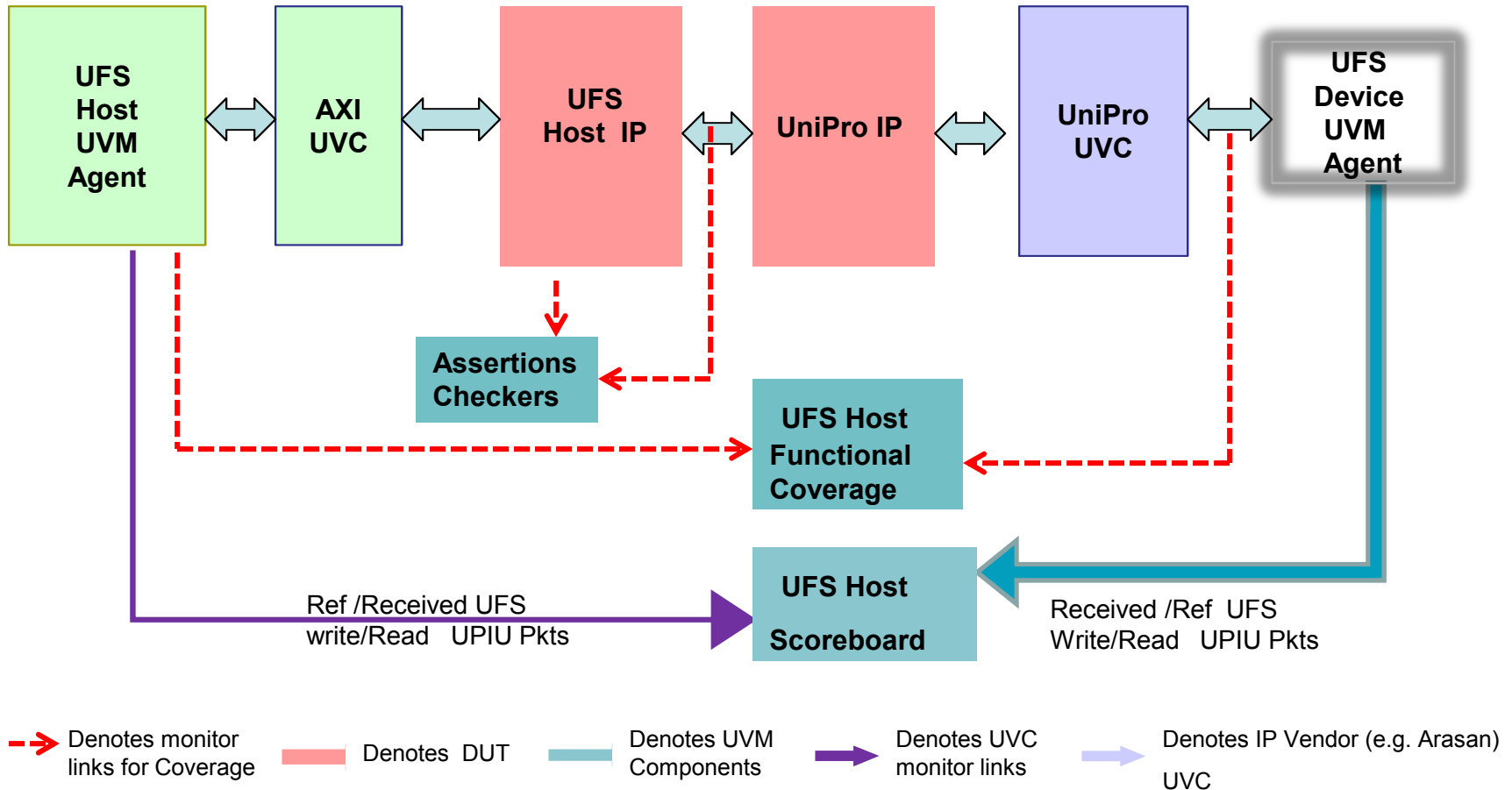


M-PHY Verification Before Silicon



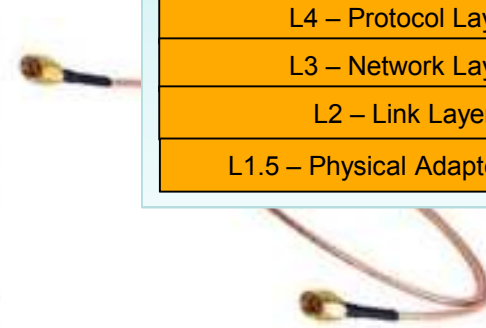
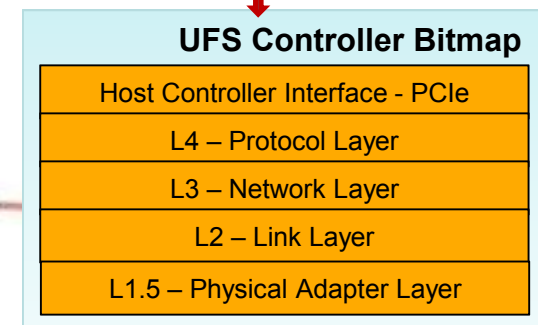
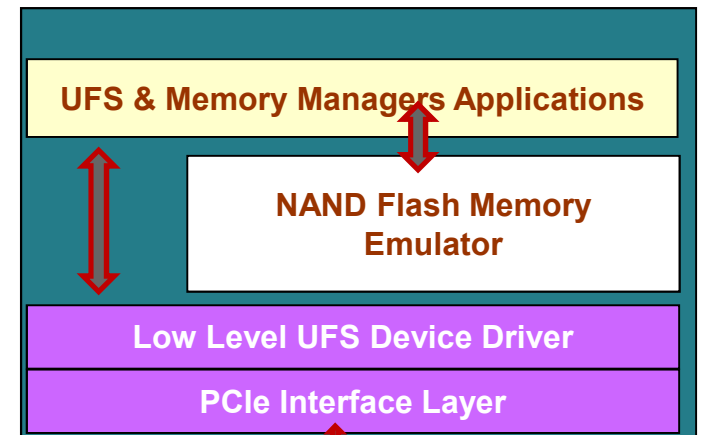
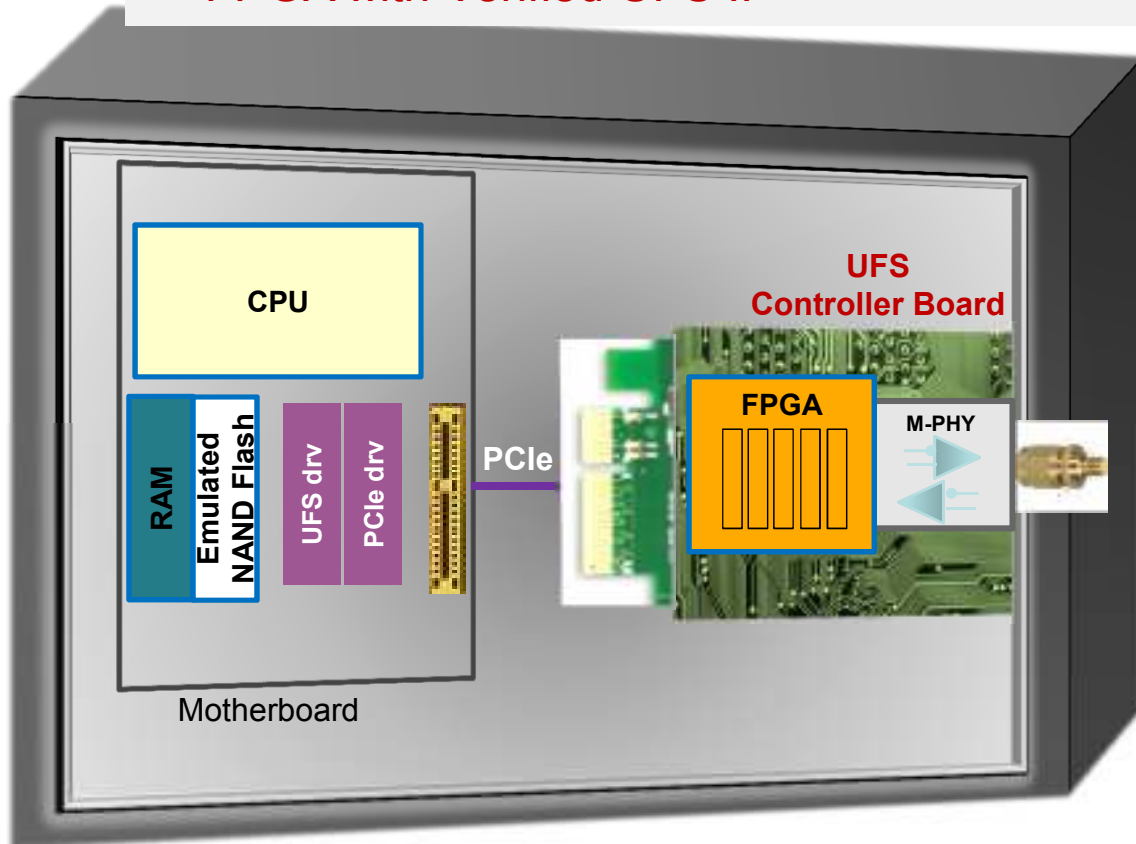
Verifying Complete UFS Before Silicon

UFS-HCI + UniPro

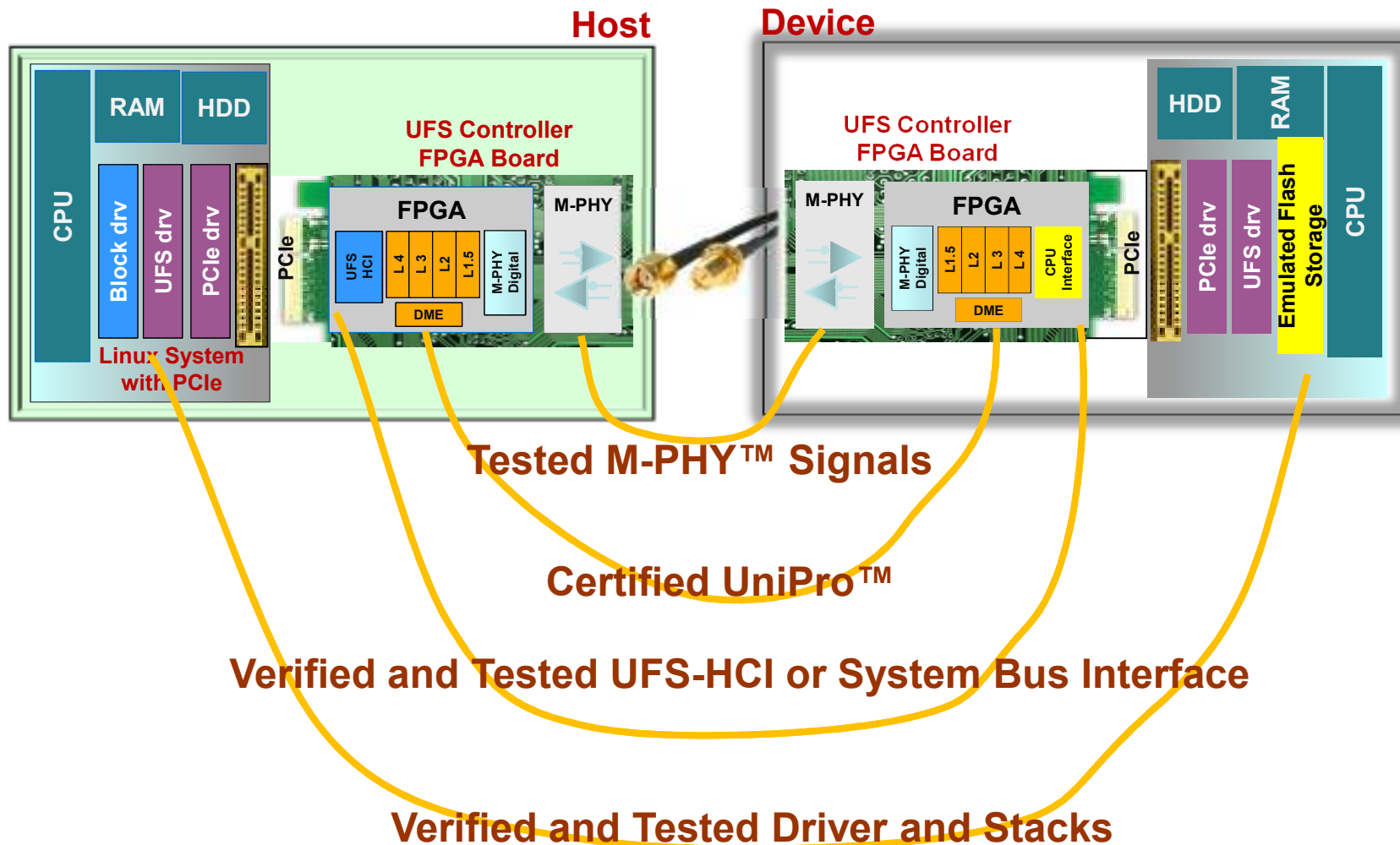


Migrate to FPGA based System

- A black-box approach enables quick access to a validation platform
- FPGA with Verified UFS IP



FPGA based System for Device Validation & Software Development



Enabling UFS/e.MMC Design Ecosystem

- FPGA based Development Platform productized into **Validation Platform**
 - IP, software stacks and PHY come together
- Used **by IP vendor** (eg. Arasan) for Interoperability testing with other pioneers
- Used **by Test & Measurement vendors** as target platforms
 - For validation of protocol generators and analyzers
- Ultimately used **by SoC/Device vendors** as target or reference platforms for silicon validation
 - Assured of IP interoperability, compliance, and backward compatibility

Summary

- **New JEDEC storage standards** continue to evolve for new markets
 - **Early IP/SoC validation** enables compliance and compatibility for fast time-to-market
- Different SoC vendors at **different stages of spec adoption**
 - Different spec revisions from different OEM's
 - **Backward compatibility** and **Interoperability** a must among vendors
- **IP vendors** continue to
 - **Leading the pack to invest** in transforming specs to RTL and GDSII
 - Keeping **Backward Compatibility** with older standards in new designs
 - Enabling **ecosystem-wide Inter-op** and **Compliance** through
 - Software stacks
 - Hardware Validation Platforms

All these are made available before starting your SoC/Device designs !!

Design for Compliance and Compatibility

THANK YOU